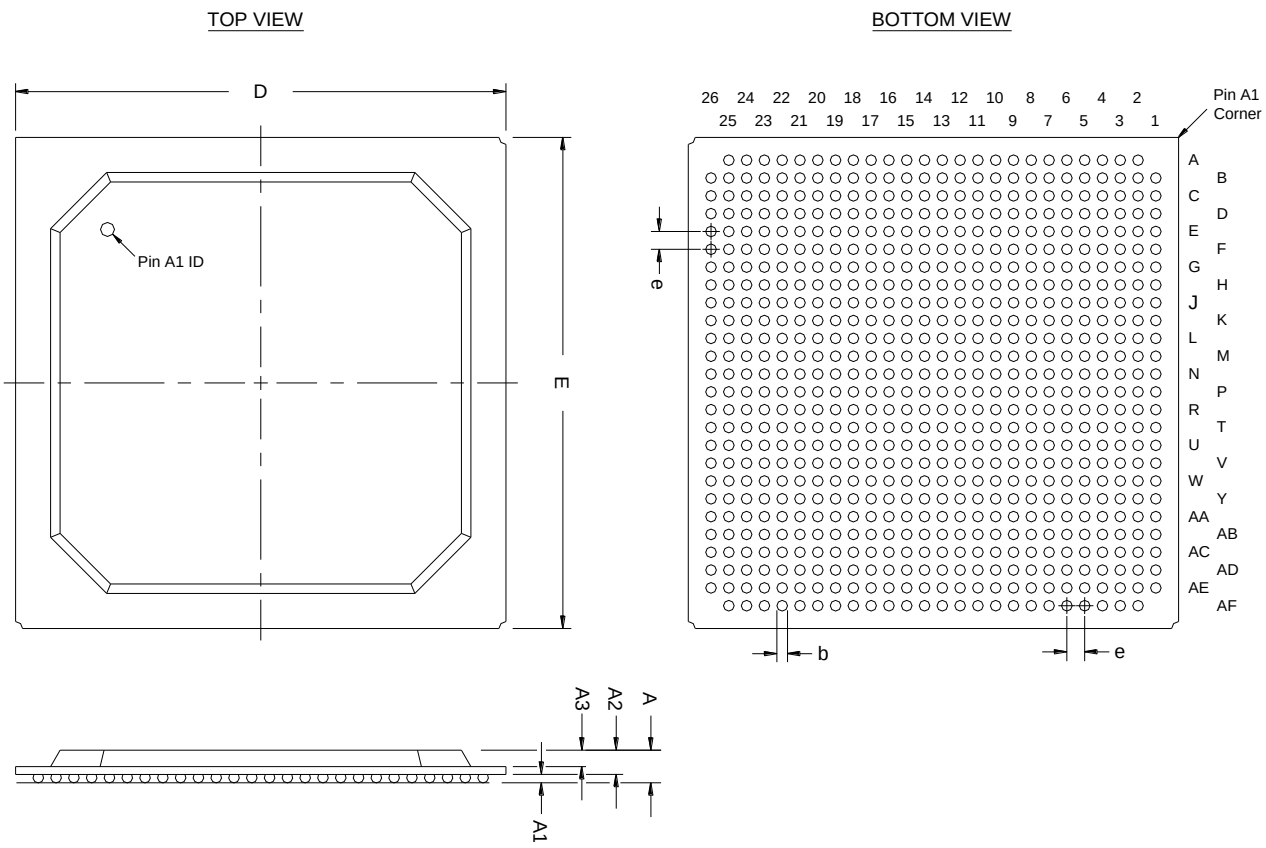
672-Pin Ball-Grid Array (BGA) - Wire Bond - A:2.50

- All dimensions and tolerances conform to ASME Y14.5M – 1994.
- Controlling dimension is in millimeters.
- Pin A1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

Package Information	
Description	**Specification**
Ordering Code Reference	B
Package Acronym	BGA
Substrate Material	BT
Solder ball composition	Regular: 63Sn:37Pb (Typ.) Pb-free: Sn:3Ag:0.5Cu (Typ.)
JEDEC Outline Reference	MS-034 Variation: BAR-2
Lead Coplanarity	0.008 inch (0.20 mm)
Weight	5.3 g (Typ.)
Moisture Sensitivity Level	Printed on moisture barrier bag

Package Outline Dimension Table			
Symbol	**Millimeters**		
	Min.	**Nom.**	**Max.**
A	2.20	2.35	2.50
A1	0.50	0.60	0.70
A2	1.50	1.75	2.00
A3	1.12	1.17	1.22
D	35.00 BSC		
E	35.00 BSC		
b	0.60	0.75	0.90
e	1.27 BSC		

Package Outline



Document Revision History

Table 1 shows the revision history for this document.

Table 1. Document Revision History

Date	Version	Changes
October 2010	1.0	Initial release

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